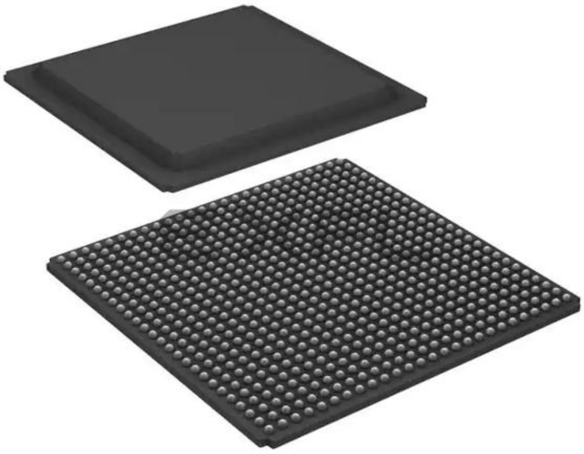
AMD Xilinx - XCV600E-8FG676C Datasheet



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Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	3456
Number of Logic Elements/Cells	15552
Total RAM Bits	294912
Number of I/O	444
Number of Gates	985882
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	676-BGA
Supplier Device Package	676-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv600e-8fg676c

Virtex-E Ordering Information

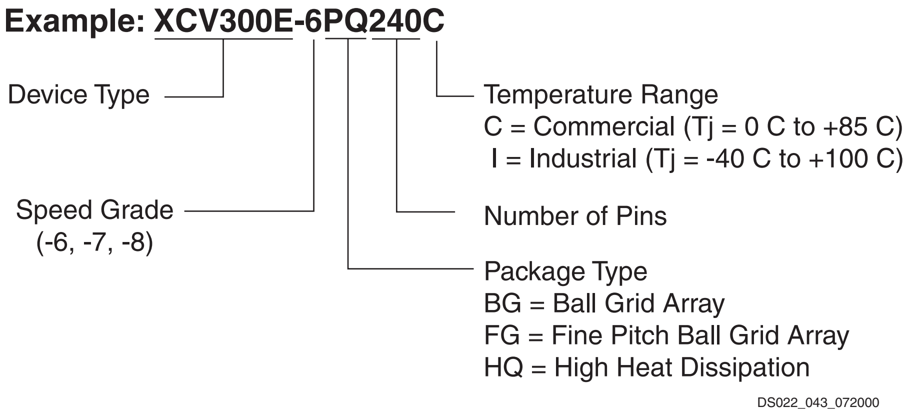

Figure 1: **Ordering Information**

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
12/7/99	1.0	Initial Xilinx release.
1/10/00	1.1	Re-released with spd.txt v. 1.18, FG860/900/1156 package information, and additional DLL, Select RAM and SelectI/O information.
1/28/00	1.2	Added Delay Measurement Methodology table, updated SelectI/O section, Figures 30, 54, & 55, text explaining Table 5, T_{BYP} values, buffered Hex Line info, p. 8, I/O Timing Measurement notes, notes for Tables 15, 16, and corrected F1156 pinout table footnote references.
2/29/00	1.3	Updated pinout tables, V_{CC} page 20, and corrected Figure 20.
5/23/00	1.4	Correction to table on p. 22.
7/10/00	1.5	• Numerous minor edits. • Data sheet upgraded to Preliminary. • Preview -8 numbers added to **Virtex-E Electrical Characteristics** tables.
8/1/00	1.6	• Reformatted entire document to follow new style guidelines. • Changed speed grade values in tables on pages 35-37.
9/20/00	1.7	• Min values added to **Virtex-E Electrical Characteristics** tables. • XCV2600E and XCV3200E numbers added to **Virtex-E Electrical Characteristics** tables (Module 3). • Corrected user I/O count for XCV100E device in Table 1 (Module 1). • Changed several pins to “No Connect in the XCV100E“ and removed duplicate V_{CCINT} pins in Table ~ (Module 4). • Changed pin J10 to “No connect in XCV600E” in Table 74 (Module 4). • Changed pin J30 to “VREF option only in the XCV600E” in Table 74 (Module 4). • Corrected pair 18 in Table 75 (Module 4) to be “AO in the XCV1000E, XCV1600E“.

Table 9 lists the total number of bits required to configure each device.

Table 9: **Virtex-E Bitstream Lengths**

Device	# of Configuration Bits
XCV50E	630,048
XCV100E	863,840
XCV200E	1,442,016
XCV300E	1, 875,648
XCV400E	2,693,440
XCV600E	3,961,632
XCV1000E	6,587,520
XCV1600E	8,308,992
XCV2000E	10,159,648
XCV2600E	12,922,336
XCV3200E	16,283,712

Slave-Serial Mode

In slave-serial mode, the FPGA receives configuration data in bit-serial form from a serial PROM or other source of serial configuration data. The serial bitstream must be set up at the DIN input pin a short time before each rising edge of an externally generated CCLK.

For more detailed information on serial PROMs, see the PROM data sheet at http://www.xilinx.com/bvdocs/publications/ds026.pdf.

Multiple FPGAs can be daisy-chained for configuration from a single source. After a particular FPGA has been configured, the data for the next device is routed to the DOUT pin. The maximum capacity for a single LOUT/DOUT write is 2^{20}-1 (1,048,575) 32-bit words, or 33,554,4000 bits. The data on the DOUT pin changes on the rising edge of CCLK.

The change of DOUT on the rising edge of CCLK differs from previous families, but does not cause a problem for mixed configuration chains. This change was made to improve serial configuration rates for Virtex and Virtex-E only chains.

Figure 13 shows a full master/slave system. A Virtex-E device in slave-serial mode should be connected as shown in the right-most device.

Slave-serial mode is selected by applying <111> or <011> to the mode pins (M2, M1, M0). A weak pull-up on the mode pins makes slave serial the default mode if the pins are left unconnected. However, it is recommended to drive the configuration mode pins externally. Figure 14 shows slave-serial mode programming switching characteristics.

Table 10 provides more detail about the characteristics shown in Figure 14. Configuration must be delayed until the $\overline{\text{INIT}}$ pins of all daisy-chained FPGAs are High.

Table 10: **Master/Slave Serial Mode Programming Switching**

	Description	Figure References	Symbol	Values	Units
CCLK	DIN setup/hold, slave mode	1/2	T_{DCC}/T_{CCD}	5.0 / 0.0	ns, min
	DIN setup/hold, master mode	1/2	T_{DSCK}/T_{CKDS}	5.0 / 0.0	ns, min
	DOUT	3	T_{CCO}	12.0	ns, max
	High time	4	T_{CCH}	5.0	ns, min
	Low time	5	T_{CCL}	5.0	ns, min
	Maximum Frequency		F_{CC}	66	MHz, max
	Frequency Tolerance, master mode with respect to nominal			+45% –30%	

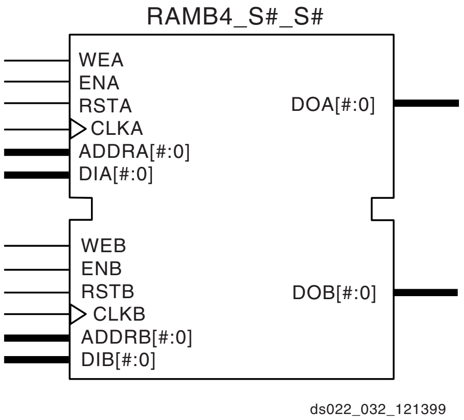

Figure 31: **Dual-Port Block SelectRAM+ Memory**

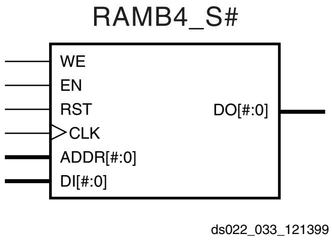

Figure 32: **Single-Port Block SelectRAM+ Memory**

Table 14: **Available Library Primitives**

Primitive	Port A Width	Port B Width
RAMB4_S1	1	N/A
RAMB4_S1_S1		1
RAMB4_S1_S2		2
RAMB4_S1_S4		4
RAMB4_S1_S8		8
RAMB4_S1_S16		16
RAMB4_S2	2	N/A
RAMB4_S2_S2		2
RAMB4_S2_S4		4
RAMB4_S2_S8		8
RAMB4_S2_S16		16
RAMB4_S4	4	N/A
RAMB4_S4_S4		4
RAMB4_S4_S8		8
RAMB4_S4_S16		16
RAMB4_S8	8	N/A
RAMB4_S8_S8		8
RAMB4_S8_S16		16
RAMB4_S16	16	N/A
RAMB4_S16_S16		16

Port Signals

Each block SelectRAM+ port operates independently of the others while accessing the same set of 4096 memory cells.

Table 15 describes the depth and width aspect ratios for the block SelectRAM+ memory.

Table 15: **Block SelectRAM+ Port Aspect Ratios**

Width	Depth	ADDR Bus	Data Bus
1	4096	ADDR<11:0>	DATA<0>
2	2048	ADDR<10:0>	DATA<1:0>
4	1024	ADDR<9:0>	DATA<3:0>
8	512	ADDR<8:0>	DATA<7:0>
16	256	ADDR<7:0>	DATA<15:0>

Clock—CLK[A|B]

Each port is fully synchronous with independent clock pins. All port input pins have setup time referenced to the port CLK pin. The data output bus has a clock-to-out time referenced to the CLK pin.

Enable—EN[A|B]

The enable pin affects the read, write and reset functionality of the port. Ports with an inactive enable pin keep the output pins in the previous state and do not write data to the memory cells.

Write Enable—WE[A|B]

Activating the write enable pin allows the port to write to the memory cells. When active, the contents of the data input bus are written to the RAM at the address pointed to by the address bus, and the new data also reflects on the data out bus. When inactive, a read operation occurs and the contents of the memory cells referenced by the address bus reflect on the data out bus.

Reset—RST[A|B]

The reset pin forces the data output bus latches to zero synchronously. This does not affect the memory cells of the RAM and does not disturb a write operation on the other port.

Address Bus—ADDR[A|B]<#:0>

The address bus selects the memory cells for read or write. The width of the port determines the required width of this bus as shown in Table 15.

Data In Bus—DI[A|B]<#:0>

The data in bus provides the new data value to be written into the RAM. This bus and the port have the same width, as shown in Table 15.

VHDL Initialization Example

```
library IEEE;
use IEEE.std_logic_1164.all;

entity MYMEM is
port (CLK, WE:in std_logic;
ADDR: in std_logic_vector(8 downto 0);
DIN: in std_logic_vector(7 downto 0);
DOUT: out std_logic_vector(7 downto 0));
end MYMEM;

architecture BEHAVE of MYMEM is
signal logic0, logic1: std_logic;

component RAMB4_S8
--synopsys translate_off
generic( INIT_00,INIT_01, INIT_02, INIT_03, INIT_04, INIT_05, INIT_06, INIT_07,
INIT_08, INIT_09, INIT_0a, INIT_0b, INIT_0c, INIT_0d, INIT_0e, INIT_0f : BIT_VECTOR(255
downto 0)
:= X"0000000000000000000000000000000000000000000000000000000000000000");
--synopsys translate_on
port (WE, EN, RST, CLK: in STD_LOGIC;
ADDR: in STD_LOGIC_VECTOR(8 downto 0);
DI: in STD_LOGIC_VECTOR(7 downto 0);
DO: out STD_LOGIC_VECTOR(7 downto 0));
end component;

--synopsys dc_script_begin
--set_attribute ram0 INIT_00
"0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF" -type string
--set_attribute ram0 INIT_01
"FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210" -type string
--synopsys dc_script_end

begin
logic0 <=’0’;
logic1 <=’1’;

ram0: RAMB4_S8
--synopsys translate_off
generic map (

INIT_00 => X"0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF",
INIT_01 => X"FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210")
--synopsys translate_on
port map (WE=>WE, EN=>logic1, RST=>logic0, CLK=>CLK,ADDR=>ADDR, DI=>DIN, DO=>DOUT);

end BEHAVE;
```

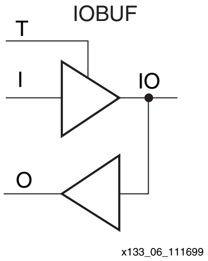

Figure 42: **Input/Output Buffer Symbol (IOBUF)**

The following list details variations of the IOBUF symbol.

- IOBUF
- IOBUF_S_2
- IOBUF_S_4
- IOBUF_S_6
- IOBUF_S_8
- IOBUF_S_12
- IOBUF_S_16
- IOBUF_S_24
- IOBUF_F_2
- IOBUF_F_4
- IOBUF_F_6
- IOBUF_F_8
- IOBUF_F_12
- IOBUF_F_16
- IOBUF_F_24
- IOBUF_LVCMOS2
- IOBUF_PCI33_3
- IOBUF_PCI66_3
- IOBUF_GTL
- IOBUF_GTLP
- IOBUF_HSTL_I
- IOBUF_HSTL_III
- IOBUF_HSTL_IV
- IOBUF_SSTL3_I
- IOBUF_SSTL3_II
- IOBUF_SSTL2_I
- IOBUF_SSTL2_II
- IOBUF_CTT
- IOBUF_AGP
- IOBUF_LVCMOS18
- IOBUF_LVDS
- IOBUF_LVPECL

When the IOBUF symbol used supports an I/O standard that requires a differential amplifier input, the IOBUF automatically configures with a differential amplifier input buffer. The low-voltage I/O standards with a differential amplifier input require an external reference voltage input V_{REF}.

The voltage reference signal is “banked” within the Virtex-E device on a half-edge basis such that for all packages there are eight independent V_{REF} banks internally. See Figure 38, page 34 for a representation of the Virtex-E I/O banks. Within each bank approximately one of every six I/O pins is automatically configured as a V_{REF} input. After placing a differential amplifier input signal within a given V_{REF} bank, the same external source must drive all I/O pins configured as a V_{REF} input.

IOBUF placement restrictions require any differential amplifier input signals within a bank be of the same standard.

The Virtex-E series supports eight banks for the HQ and PQ packages. The CS package supports four V_{CCO} banks.

Additional restrictions on the Virtex-E SelectI/O IOBUF placement require that within a given V_{CCO} bank each IOBUF must share the same output source drive voltage. Input buffers of any type and output buffers that do not require V_{CCO} can be placed within the same V_{CCO} bank. The LOC property can specify a location for the IOBUF.

An optional delay element is associated with the input path in each IOBUF. When the IOBUF drives an input flip-flop within the IOB, the delay element activates by default to ensure a zero hold-time requirement. Override this default with the NODELAY=TRUE property.

In the case when the IOBUF does not drive an input flip-flop within the IOB, the delay element de-activates by default to provide higher performance. To delay the input signal, activate the delay element with the DELAY=TRUE property.

3-state output buffers and bidirectional buffers can have either a weak pull-up resistor, a weak pull-down resistor, or a weak “keeper” circuit. Control this feature by adding the appropriate symbol to the output net of the IOBUF (PULLUP, PULLDOWN, or KEEPER).

SelectI/O Properties

Access to some of the SelectI/O features (for example, location constraints, input delay, output drive strength, and slew rate) is available through properties associated with these features.

Input Delay Properties

An optional delay element is associated with each IBUF. When the IBUF drives a flip-flop within the IOB, the delay element activates by default to ensure a zero hold-time requirement. Use the NODELAY=TRUE property to override this default.

In the case when the IBUF does not drive a flip-flop within the IOB, the delay element by default de-activates to provide higher performance. To delay the input signal, activate the delay element with the DELAY=TRUE property.

The register elements can be packed in the IOB using the IOB property to TRUE on the register or by using the “map -pr [i|o|b]” where “i” is inputs only, “o” is outputs only and “b” is both inputs and outputs.

To improve design coding times VHDL and Verilog synthesis macro libraries have been developed to explicitly create these structures. The input library macros are listed below. The 3-state is configured to be 3-stated at GSR and when the PRE,CLR,S or R is asserted and shares it's clock enable with the output register. If this is not desirable then the library can be updated by the user for the desired functionality. The O and OB inputs to the macros are the external net connections.

Creating a LVDS Bidirectional Buffer

LVDS bidirectional buffers can be placed in a wide number of IOB locations. The exact locations are dependent on the package used. The Virtex-E package information lists the possible locations as IO_L#P for the P-side and IO_L#N for the N-side, where # is the pair number.

HDL Instantiation

Both bidirectional buffers are required to be instantiated in the design and placed on the correct IO_L#P and IO_L#N locations. The IOB must have the same net source the following pins, clock (C), set/reset (SR), 3-state (T), 3-state clock enable (TCE), output (O), output clock enable (OCE). In addition, the output (O) pins must be inverted with respect to each other, and if output registers are used, the INIT states must be opposite values (one HIGH and one LOW). If 3-state registers are used, they must be initialized to the same state. Failure to follow these rules leads to DRC errors in the software.

VHDL Instantiation

```
data0_p:   IOBUF_LVDS port map
(I=>data_out(0), T=>data_tri,
IO=>data_p(0), O=>data_int(0));

data0_inv: INV        port map
(I=>data_out(0),   O=>data_n_out(0));

data0_n   : IOBUF_LVDS port map
(I=>data_n_out(0), T=>data_tri,
IO=>data_n(0), O=>open);
```

Verilog Instantiation

```
IOBUF_LVDS data0_p(.I(data_out[0]),
.T(data_tri), .IO(data_p[0]),
.O(data_int[0]);

INV        data0_inv (.I(data_out[0],
.O(data_n_out[0]);

IOBUF_LVDS
data0_n(.I(data_n_out[0]),.T(data_tri),.
IO(data_n[0]).O());
```

Location Constraints

All LVDS buffers must be explicitly placed on a device. For the output buffers this can be done with the following constraint in the .ucf or .ncf file.

```
NET data_p<0> LOC = D28; # IO_L0P

NET data_n<0> LOC = B29; # IO_L0N
```

Synchronous vs. Asynchronous Bidirectional Buffers

If the output side of the bidirectional buffers are synchronous (registered in the IOB), then any IO_L#P|N pair can be used. If the output side of the bidirectional buffers are asynchronous (no output register), then they must use one of the pairs that is a part of the asynchronous LVDS IOB group. This applies for either the 3-state pin or the data out pin.

The LVDS pairs that can be used as asynchronous bidirectional buffers are listed in the Virtex-E pinout tables. Some pairs are marked as asynchronous capable for all devices in that package, and others are marked as available only for that device in the package. If the device size might change at some point in the product’s lifetime, then only the common pairs for all packages should be used.

Adding Output and 3-State Registers

All LVDS buffers can have an output and input registers in the IOB. The output registers must be in both the P-side and N-side IOBs, the input register is only in the P-side. All the normal IOB register options are available (FD, FDE, FDC, FDCE, FDP, FDPE, FDR, FDRE, FDS, FDSE, LD, LDE, LDC, LDCE, LDP, LDPE). The register elements can be inferred or explicitly instantiated in the HDL code. Special care must be taken to insure that the D pins of the registers are inverted and that the INIT states of the registers are opposite. The 3-state (T), 3-state clock enable (CE), clock pin (C), output clock enable (CE), and set/reset (CLR/PRE or S/R) pins must connect to the same source. Failure to do this leads to a DRC error in the software.

The register elements can be packed in the IOB using the IOB property to TRUE on the register or by using the “map -pr [i|o|b]” where “i” is inputs only, “o” is outputs only and “b” is both inputs and outputs. To improve design coding times VHDL and Verilog synthesis macro libraries have been developed to explicitly create these structures. The bidirectional I/O library macros are listed in Table 44. The 3-state is configured to be 3-stated at GSR and when the PRE,CLR,S or R is asserted and shares its clock enable with the output and input register. If this is not desirable then the library can be updated be the user for the desired functionality. The I/O and IOB inputs to the macros are the external net connections.

Power-On Power Supply Requirements

Xilinx FPGAs require a certain amount of supply current during power-on to insure proper device operation. The actual current consumed depends on the power-on ramp rate of the power supply. This is the time required to reach the nominal power supply voltage of the device[1] from 0V. The fastest ramp rate is 0V to nominal voltage in 2 ms, and the slowest allowed ramp rate is 0V to nominal voltage in 50 ms. For more details on power supply requirements, see XAPP158 on www.xilinx.com.

Product (Commercial Grade)	Description(2)	Current Requirement(3)
XCV50E - XCV600E	Minimum required current supply	500 mA
XCV812E - XCV2000E	Minimum required current supply	1 A
XCV2600E - XCV3200E	Minimum required current supply	1.2 A
Virtex-E Family, Industrial Grade	Minimum required current supply	2 A

Notes:

1. Ramp rate used for this specification is from 0 - 1.8 V DC. Peak current occurs on or near the internal power-on reset threshold and lasts for less than 3 ms.
2. Devices are guaranteed to initialize properly with the minimum current available from the power supply as noted above.
3. Larger currents might result if ramp rates are forced to be faster.

DC Input and Output Levels

Values for V_{IL} and V_{IH} are recommended input voltages. Values for I_{OL} and I_{OH} are guaranteed over the recommended operating conditions at the V_{OL} and V_{OH} test points. Only selected standards are tested. These are chosen to ensure that all standards meet their specifications. The selected standards are tested at minimum V_{CCO} with the respective V_{OL} and V_{OH} voltage levels shown. Other standards are sample tested.

Input/Output Standard	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}
	V, Min	V, Max	V, Min	V, Max	V, Max	V, Min	mA	mA
LVTTL(1)	– 0.5	0.8	2.0	3.6	0.4	2.4	24	– 24
LVCMOS2	– 0.5	0.7	1.7	2.7	0.4	1.9	12	– 12
LVCMOS18	– 0.5	35% V_{CCO}	65% V_{CCO}	1.95	0.4	V_{CCO} – 0.4	8	– 8
PCI, 3.3 V	– 0.5	30% V_{CCO}	50% V_{CCO}	V_{CCO} + 0.5	10% V_{CCO}	90% V_{CCO}	Note 2	Note 2
GTL	– 0.5	V_{REF} – 0.05	V_{REF} + 0.05	3.6	0.4	n/a	40	n/a
GTL+	– 0.5	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.6	n/a	36	n/a
HSTL I(3)	– 0.5	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCO} – 0.4	8	–8
HSTL III	– 0.5	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCO} – 0.4	24	–8
HSTL IV	– 0.5	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCO} – 0.4	48	–8
SSTL3 I	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.6	V_{REF} + 0.6	8	–8
SSTL3 II	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.8	V_{REF} + 0.8	16	–16
SSTL2 I	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.61	V_{REF} + 0.61	7.6	–7.6
SSTL2 II	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.80	V_{REF} + 0.80	15.2	–15.2

DLL Clock Tolerance, Jitter, and Phase Information

All DLL output jitter and phase specifications determined through statistical measurement at the package pins using a clock mirror configuration and matched drivers.

			CLKDLLHF		CLKDLL		
Description	**Symbol**	**F_{CLKIN}**	**Min**	**Max**	**Min**	**Max**	**Units**
Input Clock Period Tolerance	T_{IPTOL}		-	1.0	-	1.0	ns
Input Clock Jitter Tolerance (Cycle to Cycle)	T_{IJITCC}		-	± 150	-	± 300	ps
Time Required for DLL to Acquire Lock(6)	T_{LOCK}	> 60 MHz	-	20	-	20	µs
		50 - 60 MHz	-	-	-	25	µs
		40 - 50 MHz	-	-	-	50	µs
		30 - 40 MHz	-	-	-	90	µs
		25 - 30 MHz	-	-	-	120	µs
Output Jitter (cycle-to-cycle) for any DLL Clock Output(1)	T_{OJITCC}			± 60		± 60	ps
Phase Offset between CLKIN and CLKO(2)	T_{PHIO}			± 100		± 100	ps
Phase Offset between Clock Outputs on the DLL(3)	T_{PHOO}			± 140		± 140	ps
Maximum Phase Difference between CLKIN and CLKO(4)	T_{PHIOM}			± 160		± 160	ps
Maximum Phase Difference between Clock Outputs on the DLL(5)	T_{PHOOM}			± 200		± 200	ps

Notes:

1. **Output Jitter** is cycle-to-cycle jitter measured on the DLL output clock and is based on a maximum tap delay resolution, *excluding* input clock jitter.
2. **Phase Offset between CLKIN and CLKO** is the worst-case fixed time difference between rising edges of CLKIN and CLKO, *excluding* Output Jitter and input clock jitter.
3. **Phase Offset between Clock Outputs on the DLL** is the worst-case fixed time difference between rising edges of any two DLL outputs, *excluding* Output Jitter and input clock jitter.
4. **Maximum Phase Difference between CLKIN an CLKO** is the sum of Output Jitter and Phase Offset between CLKIN and CLKO, or the greatest difference between CLKIN and CLKO rising edges due to DLL alone (*excluding* input clock jitter).
5. **Maximum Phase DIfference between Clock Outputs on the DLL** is the sum of Output JItter and Phase Offset between any DLL clock outputs, or the greatest difference between any two DLL output rising edges sue to DLL alone (*excluding* input clock jitter).
6. Add 30% to the value for industrial grade parts.

CS144 Chip-Scale Package

XCV50E, XCV100E, XCV200E, XCV300E and XCV400E devices in CS144 Chip-scale packages have footprint compatibility. In the CS144 package, bank pairs that share a side are internally interconnected, permitting four choices for V_{CCO}. See Table 3.

Table 3: **I/O Bank Pairs and Shared Vcco Pins**

Paired Banks	Shared V_{CCO} Pins
Banks 0 & 1	A2, A13, D7
Banks 2 & 3	B12, G11, M13
Banks 4 & 5	N1, N7, N13
Banks 6 & 7	B2, G2, M2

Pins labeled I0_VREF can be used as either in all parts unless device-dependent, as indicated in the footnotes. If the pin is not used as V_{REF}, it can be used as general I/O. Immediately following Table 4, see Table 5 is Differential Pair information.

Table 4: **CS144 — XCV50E, XCV100E, XCV200E**

Bank	Pin Description	Pin #
0	GCK3	A6
0	IO	B3
0	IO_VREF_L0N_YY	B4[2]
0	IO_L0P_YY	A4
0	IO_L1N_YY	B5
0	IO_L1P_YY	A5
0	IO_LVDS_DLL_L2N	C6
0	IO_VREF	A3[1]
0	IO_VREF	C4
0	IO_VREF	D6
1	GCK2	A7
1	IO	A8
1	IO_LVDS_DLL_L2P	B7
1	IO_L3N_YY	C8
1	IO_L3P_YY	D8
1	IO_L4N_YY	C9
1	IO_VREF_L4P_YY	D9[2]
1	IO_WRITE_L5N_YY	C10
1	IO_CS_L5P_YY	D10
1	IO_VREF	A10
1	IO_VREF	B8
1	IO_VREF	B10[1]
2	IO	D12
2	IO	F12
2	IO_DOUT_BUSY_L6P_YY	C11
2	IO_DIN_D0_L6N_YY	C12
2	IO_D1_L7N	E10
2	IO_VREF_L7P	D13[2]
2	IO_L8N_YY	E13
2	IO_D2_L8P_YY	E12
2	IO_D3_L9N	F11
2	IO_VREF_L9P	F10
2	IO_L10P	F13
2	IO_VREF	C13[1]
2	IO_VREF	D11
3	IO	H13
3	IO	K13
3	IO_L10N	G13
3	IO_VREF_L11N	H11
3	IO_D4_L11P	H12
3	IO_D5_L12N_YY	J13
3	IO_L12P_YY	H10
3	IO_VREF_L13N	J10[2]
3	IO_D6_L13P	J11
3	IO_INIT_L14N_YY	L13
3	IO_D7_L14P_YY	K10
3	IO_VREF	K11[1]
3	IO_VREF	K12
4	GCK0	K7
4	IO	M8
4	IO	M10

Table 11: **BG352 Differential Pin Pair Summary XCV100E, XCV200E, XCV300E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
55	5	AC13	AD14	√	GCLK LVDS 1/0
56	5	AD15	AC15	√	VREF_5
57	5	AE16	AE17	√	-
58	5	AC16	AF18	2	-
59	5	AD17	AC17	√	-
60	5	AD18	AC18	√	VREF_5
61	5	AF20	AE20	1	-
62	5	AE21	AD20	√	VREF_5
63	5	AF23	AE22	√	-
64	5	AC21	AE23	√	VREF_5
65	6	AD25	AC24	√	-
66	6	AC26	AD26	√	VREF_6
67	6	AB25	AA24	√	-
68	6	Y24	AA25	√	VREF_6
69	6	W24	V23	2	-
70	6	U23	Y26	√	VREF_6
71	6	U24	V25	√	-
72	6	U25	T23	1	-
73	6	T26	T25	√	-
74	6	R25	R24	√	VREF_6
75	6	P24	R26	2	-
76	7	N24	N25	√	-
77	7	M24	M25	2	-
78	7	L26	M23	√	VREF_7
79	7	L24	K25	√	-
80	7	J25	J26	1	-
81	7	H25	K23	√	-
82	7	G26	J23	√	VREF_7
83	7	H24	G25	1	-
84	7	D26	G24	√	VREF_7
85	7	F24	E25	√	-
86	7	E24	D25	√	VREF_7

Notes:
1. AO in the XCV100E.
2. AO in the XCV200E.

BG432 Ball Grid Array Packages

XCV300E, XCV400E, and XCV600E devices in BG432 Ball Grid Array packages have footprint compatibility. Pins labeled I0_VREF can be used as either in all parts unless device-dependent as indicated in the footnotes. If the pin is not used as V_{REF}, it can be used as general I/O. Immediately following Table 12, see Table 13 for Differential Pair information.

Table 12: **BG432 — XCV300E, XCV400E, XCV600E**

Bank	Pin Description	Pin #
0	GCK3	D17
0	IO	A22
0	IO	A26
0	IO	B20
0	IO	C23
0	IO	C28
0	IO_L0N_Y	B29
0	IO_L0P_Y	D27
0	IO_L1N_YY	B28
0	IO_L1P_YY	C27
0	IO_VREF_L2N_YY	D26
0	IO_L2P_YY	A28
0	IO_L3N_Y	B27
0	IO_L3P_Y	C26
0	IO_L4N_YY	D25
0	IO_L4P_YY	A27
0	IO_VREF_L5N_YY	D24
0	IO_L5P_YY	C25
0	IO_L6N_Y	B25
0	IO_L6P_Y	D23
0	IO_VREF_L7N_Y	C24[1]
0	IO_L7P_Y	B24
0	IO_VREF_L8N_YY	D22
0	IO_L8P_YY	A24
0	IO_L9N_YY	C22
0	IO_L9P_YY	B22
0	IO_L10N_YY	C21
0	IO_L10P_YY	D20
0	IO_L11N_YY	B21
0	IO_L11P_YY	C20

Table 12: **BG432 — XCV300E, XCV400E, XCV600E**

Bank	Pin Description	Pin #
2	IO_L41N_Y	H2
2	IO_VREF_L42P_Y	H1[1]
2	IO_L42N_Y	J4
2	IO_VREF_L43P_YY	J2
2	IO_D1_L43N_YY	K4
2	IO_D2_L44P_YY	K2
2	IO_L44N_YY	K1
2	IO_L45P_Y	L2
2	IO_L45N_Y	M4
2	IO_L46P_Y	M3
2	IO_L46N_Y	M2
2	IO_L47P_Y	N4
2	IO_L47N_Y	N3
2	IO_VREF_L48P_YY	N1
2	IO_D3_L48N_YY	P4
2	IO_L49P_Y	P3
2	IO_L49N_Y	P2
2	IO_VREF_L50P_Y	R3[2]
2	IO_L50N_Y	R4
2	IO_L51P_YY	R1
2	IO_L51N_YY	T3
3	IO	AA2
3	IO	AC2
3	IO	AE2
3	IO	U3
3	IO	W1
3	IO_L52P_Y	U4
3	IO_VREF_L52N_Y	U2[2]
3	IO_L53P_Y	U1
3	IO_L53N_Y	V3
3	IO_D4_L54P_YY	V4
3	IO_VREF_L54N_YY	V2
3	IO_L55P_Y	W3
3	IO_L55N_Y	W4
3	IO_L56P_Y	Y1

Table 12: **BG432 — XCV300E, XCV400E, XCV600E**

Bank	Pin Description	Pin #
3	IO_L56N_Y	Y3
3	IO_L57P_Y	Y4
3	IO_L57N_Y	Y2
3	IO_L58P_YY	AA3
3	IO_D5_L58N_YY	AB1
3	IO_D6_L59P_YY	AB3
3	IO_VREF_L59N_YY	AB4
3	IO_L60P_Y	AD1
3	IO_VREF_L60N_Y	AC3[1]
3	IO_L61P_Y	AC4
3	IO_L61N_Y	AD2
3	IO_L62P_YY	AD3
3	IO_VREF_L62N_YY	AD4
3	IO_L63P_Y	AF2
3	IO_L63N_Y	AE3
3	IO_L64P	AE4
3	IO_L64N	AG1
3	IO_L65P_Y	AG2
3	IO_VREF_L65N_Y	AF3
3	IO_L66P_Y	AF4
3	IO_L66N_Y	AH1
3	IO_L67P	AH2
3	IO_L67N	AG3
3	IO_D7_L68P_YY	AG4
3	IO_INIT_L68N_YY	AJ2
3	IO	T2
4	GCK0	AL16
4	IO	AH10
4	IO	AJ11
4	IO	AK7
4	IO	AL12
4	IO	AL15
4	IO_L69P_YY	AJ4
4	IO_L69N_YY	AK3
4	IO_L70P_Y	AH5

Table 14: **BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin#	See Note
3	IO_D4_L73P_YY	W4	
3	IO_VREF_L73N_YY	W5	
3	IO_L74P_Y	Y3	
3	IO_L74N_Y	Y4	
3	IO_L75P_Y	AA1	
3	IO_L75N_Y	Y5	
3	IO_L76P_Y	AA3	
3	IO_VREF_L76N_Y	AA4	3
3	IO_L77P_Y	AB3	
3	IO_L77N_Y	AA5	
3	IO_L78P_Y	AC1	
3	IO_L78N_Y	AB4	
3	IO_L79P_YY	AC3	
3	IO_D5_L79N_YY	AB5	
3	IO_D6_L80P_YY	AC4	
3	IO_VREF_L80N_YY	AD3	
3	IO_L81P_Y	AE1	
3	IO_L81N_Y	AC5	
3	IO_L82P_Y	AD4	
3	IO_VREF_L82N_Y	AF1	4
3	IO_L83P_Y	AF2	
3	IO_L83N_Y	AD5	
3	IO_L84P_Y	AG2	
3	IO_VREF_L84N_Y	AE4	1
3	IO_L85P_YY	AH1	
3	IO_VREF_L85N_YY	AE5	
3	IO_L86P_Y	AF4	
3	IO_L86N_Y	AJ1	
3	IO_L87P_Y	AJ2	
3	IO_L87N_Y	AF5	
3	IO_L88P_Y	AG4	
3	IO_VREF_L88N_Y	AK2	
3	IO_L89P_Y	AJ3	
3	IO_L89N_Y	AG5	
3	IO_L90P_Y	AL1	

Table 14: **BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin#	See Note
3	IO_VREF_L90N_Y	AH4	3
3	IO_D7_L91P_YY	AJ4	
3	IO_INIT_L91N_YY	AH5	
3	IO	U4	
4	GCK0	AL17	
4	IO	AJ8	
4	IO	AJ11	
4	IO	AK6	
4	IO	AK9	
4	IO_L92P_YY	AL4	
4	IO_L92N_YY	AJ6	
4	IO_L93P_Y	AK5	
4	IO_VREF_L93N_Y	AN3	3
4	IO_L94P_YY	AL5	
4	IO_L94N_YY	AJ7	
4	IO_VREF_L95P_YY	AM4	
4	IO_L95N_YY	AM5	
4	IO_L96P_Y	AK7	
4	IO_L96N_Y	AL6	
4	IO_L97P_YY	AM6	
4	IO_L97N_YY	AN6	
4	IO_VREF_L98P_YY	AL7	
4	IO_L98N_YY	AJ9	
4	IO_L99P_Y	AN7	
4	IO_VREF_L99N_Y	AL8	1
4	IO_L100P_Y	AM8	
4	IO_L100N_Y	AJ10	
4	IO_VREF_L101P_Y	AL9	4
4	IO_L101N_Y	AM9	
4	IO_L102P_Y	AK10	
4	IO_L102N_Y	AN9	
4	IO_VREF_L103P_YY	AL10	
4	IO_L103N_YY	AM10	
4	IO_L104P_YY	AL11	

Table 16: **FG256 Package — XCV50E, XCV100E, XCV200E, XCV300E**

Bank	Pin Description	Pin #
7	IO_L74N_Y	G4
7	IO_VREF_L74P_Y	H3
7	IO_L75N_YY	G2
7	IO_L75P_YY	F5
7	IO_L76N	F4
7	IO_L76P	F1
7	IO_L77N_YY	G3
7	IO_L77P_YY	F2
7	IO_L78N_Y	E1
7	IO_VREF_L78P_Y	D1[1]
7	IO_L79N	E4
7	IO_L79P	E2
7	IO_L80N_Y	F3
7	IO_VREF_L80P_Y	C1
7	IO_L81N_YY	D2
7	IO_L81P_YY	E3
7	IO_VREF_L82N	B1[2]
7	IO_L82P	A2
2	CCLK	D15
3	DONE	R14
NA	DXN	R4
NA	DXP	P4
NA	M0	N3
NA	M1	P2
NA	M2	R3
NA	PROGRAM	P15
NA	TCK	C4
NA	TDI	A15
2	TDO	B14
NA	TMS	D3
NA	VCCINT	C3
NA	VCCINT	C14
NA	VCCINT	D4

Table 16: **FG256 Package — XCV50E, XCV100E, XCV200E, XCV300E**

Bank	Pin Description	Pin #
NA	VCCINT	D13
NA	VCCINT	E5
NA	VCCINT	E12
NA	VCCINT	M5
NA	VCCINT	M12
NA	VCCINT	N4
NA	VCCINT	N13
NA	VCCINT	P3
NA	VCCINT	P14
0	VCCO	F8
0	VCCO	E8
1	VCCO	F9
1	VCCO	E9
2	VCCO	H12
2	VCCO	H11
3	VCCO	J12
3	VCCO	J11
4	VCCO	M9
4	VCCO	L9
5	VCCO	M8
5	VCCO	L8
6	VCCO	J6
6	VCCO	J5
7	VCCO	H6
7	VCCO	H5
NA	GND	T16
NA	GND	T1
NA	GND	R15
NA	GND	R2
NA	GND	L11
NA	GND	L10
NA	GND	L7
NA	GND	L6

Table 17: **FG256 Differential Pin Pair Summary XCV50E, XCV100E, XCV200E, XCV300E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
19	2	C15	D14	√	DIN, D0
20	2	B16	E13	6	VREF
21	2	C16	E14	√	-
22	2	F13	E15	1	VREF
23	2	F12	D16	5	-
24	2	F14	E16	3	D1
25	2	F15	G13	√	D2
26	2	F16	G12	6	-
27	2	G15	G14	√	-
28	2	H13	G16	3	D3
29	2	J13	H15	4	-
30	2	H14	H16	√	-
31	3	K15	J14	4	-
32	3	J16	K16	3	VREF
33	3	K12	L15	√	-
34	3	K13	L16	6	-
35	3	K14	M16	√	D5
36	3	N16	L13	3	VREF
37	3	P16	L12	5	-
38	3	M15	L14	1	VREF
39	3	M14	R16	√	-
40	3	M13	T15	6	VREF
41	3	N14	N15	√	INIT
42	4	T14	P13	√	-
43	4	P12	R13	7	VREF
44	4	N12	T13	√	-
45	4	T12	P11	√	VREF
46	4	R12	N11	2	-
47	4	T11	M11	√	VREF
48	4	R11	T10	√	-
49	4	R10	M10	1	-
50	4	P9	T9	1	VREF
51	4	N10	R9	1	-
52	5	N9	T8	NA	IO_LVDS_DLL
53	5	R7	P8	1	VREF
54	5	P7	T6	1	-
55	5	M7	R6	√	-
56	5	P6	R5	√	VREF
57	5	N6	T5	2	-
58	5	M6	T4	√	VREF
59	5	T3	P5	√	-
60	5	T2	N5	7	VREF
61	6	R1	M3	√	-
62	6	N2	M4	6	VREF
63	6	P1	L5	√	-
64	6	L3	N1	1	VREF
65	6	L4	M2	5	-
66	6	K4	M1	3	VREF
67	6	L1	L2	√	-
68	6	K1	K3	6	-
69	6	K5	K2	√	-
70	6	J1	J3	3	VREF
71	6	H1	J4	4	-
72	7	H4	G1	√	-
73	7	H2	G5	4	-
74	7	H3	G4	3	VREF
75	7	F5	G2	√	-
76	7	F1	F4	6	-
77	7	F2	G3	√	-
78	7	D1	E1	3	VREF
79	7	E2	E4	5	-
80	7	C1	F3	1	VREF
81	7	E3	D2	√	-
82	7	A2	B1	6	VREF

Notes:

1. AO in the XCV50E, 200E, 300E.
2. AO in the XCV50E, 200E.
3. AO in the XCV50E, 300E.
4. AO in the XCV100E, 200E.
5. AO in the XCV200E.
6. AO in the XCV100E.
7. AO in the XCV50E.

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
7	IO	D2
7	IO	D3
7	IO	E1
7	IO	G1
7	IO	H2
7	IO	J1[1]
7	IO	L1[1]
7	IO	M1[1]
7	IO	N1[1]
7	IO_L160N_YY	N5
7	IO_L160P_YY	N8
7	IO_L161N_YY	N6
7	IO_L161P_YY	N3
7	IO_L162N_Y	N4
7	IO_VREF_L162P_Y	M2
7	IO_L163N_Y	N7
7	IO_L163P_Y	M7
7	IO_L164N_YY	M6
7	IO_L164P_YY	M3
7	IO_L165N_YY	M4
7	IO_VREF_L165P_YY	M5
7	IO_L166N_Y	L3
7	IO_L166P_Y	L7
7	IO_L167N_Y	L6
7	IO_L167P_Y	K2
7	IO_L168N_Y	L4
7	IO_L168P_Y	K1
7	IO_L169N_Y	K3
7	IO_L169P_Y	L5
7	IO_L170N_YY	K5
7	IO_L170P_YY	J3
7	IO_L171N_YY	K4
7	IO_L171P_YY	J4
7	IO_L172N_YY	H3
7	IO_VREF_L172P_YY	K6
7	IO_L173N_YY	K7
7	IO_L173P_YY	G3
7	IO_L174N_Y	J5
7	IO_VREF_L174P_Y	H1[2]
7	IO_L175N_Y	G2
7	IO_L175P_Y	J6
7	IO_L176N_YY	J7
7	IO_L176P_YY	F1
7	IO_L177N_YY	H4
7	IO_VREF_L177P_YY	G4
7	IO_L178N_Y	F3
7	IO_L178P_Y	H5
7	IO_L179N_Y	E2
7	IO_L179P_Y	H6
7	IO_L180N_Y	G5
7	IO_VREF_L180P_Y	F4
7	IO_L181N_Y	H7
7	IO_L181P_Y	G6
7	IO_L182N_YY	E3
7	IO_L182P_YY	E4
2	CCLK	D24
3	DONE	AB21
NA	DXN	AB7
NA	DXP	Y8
NA	M0	AD4
NA	M1	W7
NA	M2	AB6
NA	PROGRAM	AA22
NA	TCK	E6
NA	TDI	D22
2	TDO	C23
NA	TMS	F5
NA	NC	T25
NA	NC	T2
NA	NC	P2
NA	NC	N25
NA	NC	L25

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
NA	GND	P14
NA	GND	P13
NA	GND	P12
NA	GND	P11
NA	GND	P10
NA	GND	N2
NA	GND	N17
NA	GND	N16
NA	GND	N15
NA	GND	N14
NA	GND	N13
NA	GND	N12
NA	GND	N11
NA	GND	N10
NA	GND	M17
NA	GND	M16
NA	GND	M15
NA	GND	M14
NA	GND	M13
NA	GND	M12
NA	GND	M11
NA	GND	M10
NA	GND	L17
NA	GND	L16
NA	GND	L15
NA	GND	L14
NA	GND	L13
NA	GND	L12
NA	GND	L11
NA	GND	L10
NA	GND	K17
NA	GND	K16
NA	GND	K15
NA	GND	K14
NA	GND	K13
NA	GND	K12
NA	GND	K11
NA	GND	K10
NA	GND	J25
NA	GND	J2
NA	GND	E5
NA	GND	E22
NA	GND	D4
NA	GND	D23
NA	GND	C3
NA	GND	C24
NA	GND	B9
NA	GND	B25
NA	GND	B2
NA	GND	B18
NA	GND	B14
NA	GND	AF26
NA	GND	AF1
NA	GND	AE9
NA	GND	AE25
NA	GND	AE2
NA	GND	AE18
NA	GND	AE13
NA	GND	AD3
NA	GND	AD24
NA	GND	AC4
NA	GND	AC23
NA	GND	AB5
NA	GND	AB22
NA	GND	A26
NA	GND	A1

Notes:

1. NC in the XCV400E.
2. V_{REF} or I/O option only in the XCV600E; otherwise, I/O option only.

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
NA	VCCO_1	F15
NA	VCCO_1	F19
NA	VCCO_1	F20
NA	VCCO_1	F7
NA	VCCO_1	F8
NA	VCCO_2	G6
NA	VCCO_2	H6
NA	VCCO_2	L6
NA	VCCO_2	M6
NA	VCCO_2	P6
NA	VCCO_2	R6
NA	VCCO_2	W6
NA	VCCO_2	Y6
NA	VCCO_3	AC6
NA	VCCO_3	AD6
NA	VCCO_3	AH6
NA	VCCO_3	AJ6
NA	VCCO_3	AL6
NA	VCCO_3	AM6
NA	VCCO_3	AR6
NA	VCCO_3	AT6
NA	VCCO_4	AU11
NA	VCCO_4	AU12
NA	VCCO_4	AU14
NA	VCCO_4	AU15
NA	VCCO_4	AU19
NA	VCCO_4	AU20
NA	VCCO_4	AU7
NA	VCCO_4	AU8
NA	VCCO_5	AU23
NA	VCCO_5	AU24
NA	VCCO_5	AU28
NA	VCCO_5	AU29
NA	VCCO_5	AU31
NA	VCCO_5	AU32
NA	VCCO_5	AU35
NA	VCCO_5	AU36

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
NA	VCCO_6	AC37
NA	VCCO_6	AD37
NA	VCCO_6	AH37
NA	VCCO_6	AJ37
NA	VCCO_6	AL37
NA	VCCO_6	AM37
NA	VCCO_6	AR37
NA	VCCO_6	AT37
NA	VCCO_7	G37
NA	VCCO_7	H37
NA	VCCO_7	L37
NA	VCCO_7	M37
NA	VCCO_7	P37
NA	VCCO_7	R37
NA	VCCO_7	W37
NA	VCCO_7	Y37
NA	GND	N6
NA	GND	N5
NA	GND	N38
NA	GND	N37
NA	GND	F6
NA	GND	F37
NA	GND	F30
NA	GND	F22
NA	GND	F21
NA	GND	F13
NA	GND	E5
NA	GND	E38
NA	GND	E30
NA	GND	E22
NA	GND	E21
NA	GND	E13
NA	GND	D42
NA	GND	D4
NA	GND	D39
NA	GND	D1

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
NA	GND	C42
NA	GND	C41
NA	GND	C40
NA	GND	C3
NA	GND	C2
NA	GND	C1
NA	GND	BB41
NA	GND	BB40
NA	GND	BB4
NA	GND	BB39
NA	GND	BB3
NA	GND	BB2
NA	GND	BA42
NA	GND	BA41
NA	GND	BA40
NA	GND	BA3
NA	GND	BA2
NA	GND	BA1
NA	GND	B42
NA	GND	B41
NA	GND	B40
NA	GND	B3
NA	GND	B2
NA	GND	B1
NA	GND	AY42
NA	GND	AY41
NA	GND	AY40
NA	GND	AY3
NA	GND	AY2
NA	GND	AY1
NA	GND	AW42
NA	GND	AW4
NA	GND	AW39
NA	GND	AW1
NA	GND	AV5
NA	GND	AV38
NA	GND	AV30
NA	GND	AV22
NA	GND	AV21
NA	GND	AV13
NA	GND	AU6
NA	GND	AU37
NA	GND	AU30
NA	GND	AU22
NA	GND	AU21
NA	GND	AU13
NA	GND	AK6
NA	GND	AK5
NA	GND	AK38
NA	GND	AK37
NA	GND	AB6
NA	GND	AB5
NA	GND	AB38
NA	GND	AB37
NA	GND	AA6
NA	GND	AA5
NA	GND	AA38
NA	GND	AA37
NA	GND	A41
NA	GND	A40
NA	GND	A4
NA	GND	A39
NA	GND	A3
NA	GND	A2

Notes:

1. V_{REF} or I/O option only in the XCV1600E, 2000E; otherwise, I/O option only.
2. V_{REF} or I/O option only in the XCV2000E; otherwise, I/O option only.

Table 25: **FG860 Differential Pin Pair Summary XCV1000E, XCV1600E, XCV2000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
188	5	AY27	AV28	√	-
189	5	BA27	AW29	5	-
190	5	BB28	AV29	1	-
191	5	AY28	AW30	1	-
192	5	BA28	AW31	2	-
193	5	BB29	AV31	√	-
194	5	AY29	AY32	√	VREF
195	5	AW32	BB30	2	-
196	5	AV32	AY30	2	-
197	5	BA30	AW33	√	VREF
198	5	BB31	AV33	√	-
199	5	AY34	BA31	1	VREF
200	5	AW34	BB32	1	-
201	5	BA32	AY35	√	VREF
202	5	BB33	AW35	√	-
203	5	AV35	BB34	5	-
204	5	AY36	BA34	5	-
205	5	BB35	AV36	√	VREF
206	5	BA35	AY37	√	-
207	5	BB36	BA36	5	-
208	5	AW37	BB37	1	VREF
209	5	BA37	AY38	1	-
210	5	BB38	AY39	2	-
211	6	AV42	AV41	√	-
212	6	AU41	AW40	3	-
213	6	AU42	AV39	1	-
214	6	AU38	AT41	2	VREF
215	6	AV40	AT42	4	-
216	6	AU39	AR41	2	-
217	6	AU40	AR42	1	VREF
218	6	AP42	AT38	√	-
219	6	AT39	AN41	2	-
220	6	AM40	AT40	1	-
221	6	AM41	AR38	√	VREF
222	6	AR40	AM42	√	-
223	6	AP38	AL40	5	VREF
224	6	AL42	AP39	2	-
225	6	AK40	AP40	√	VREF
226	6	AN39	AK41	√	-
227	6	AN40	AK42	2	-
228	6	AJ41	AM38	√	VREF
229	6	AM39	AJ42	√	-
230	6	AH41	AH40	3	-
231	6	AH42	AL38	1	-
232	6	AG41	AL39	2	-
233	6	AG40	AK39	4	-
234	6	AG42	AJ38	2	-
235	6	AJ39	AF42	1	VREF
236	6	AH38	AF41	√	-
237	6	AH39	AE42	2	-
238	6	AE41	AG38	1	-
239	6	AD42	AG39	√	VREF
240	6	AF39	AD40	√	-
241	6	AE38	AD41	5	-
242	6	AC40	AE39	2	-
243	6	AC41	AD38	√	VREF
244	6	AC38	AB42	√	-
245	6	AC39	AB40	2	VREF
246	7	AB39	AA41	√	-
247	7	AA39	Y41	2	VREF
248	7	Y39	Y40	√	-
249	7	W41	Y38	√	VREF
250	7	W39	W40	2	-
251	7	V41	W38	5	-
252	7	V40	V39	√	-
253	7	U39	V42	√	VREF
254	7	U38	U41	1	-
255	7	T39	U42	2	-

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
1	IO_L66P_Y	E24
1	IO_L67N_YY	A26
1	IO_VREF_L67P_YY	C25
1	IO_L68N_YY	F24
1	IO_L68P_YY	B26
1	IO_L69N	K23[5]
1	IO_L69P	F25[4]
1	IO_L70N_Y	C26
1	IO_VREF_L70P_Y	H24[2]
1	IO_L71N_Y	G24
1	IO_L71P_Y	A27
1	IO_L72N	B27[5]
1	IO_L72P	G25[4]
1	IO_L73N_YY	E26
1	IO_VREF_L73P_YY	C27
1	IO_L74N_YY	J24
1	IO_L74P_YY	B28
1	IO_L75N	K24[5]
1	IO_L75P	H25[4]
1	IO_L76N_Y	D27
1	IO_L76P_Y	F26
1	IO_L77N_Y	G26
1	IO_L77P_Y	C28
1	IO_L78N_YY	E27[5]
1	IO_L78P_YY	J25[4]
1	IO_L79N_YY	A30
1	IO_VREF_L79P_YY	H26
1	IO_L80N_YY	G27
1	IO_L80P_YY	B29
1	IO_L81N_Y	F27
1	IO_L81P_Y	C29
1	IO_L82N_Y	E28
1	IO_VREF_L82P_Y	F28
1	IO_L83N_Y	L25
1	IO_L83P_Y	B30
1	IO_L84N	B31
1	IO_L84P	E29
1	IO_WRITE_L85N_YY	A31
1	IO_CS_L85P_YY	D30
2	IO	F31[3]
2	IO	J32
2	IO	K27[3]
2	IO	K31[3]
2	IO	L28[3]
2	IO	L30[3]
2	IO	M32[3]
2	IO	N26
2	IO	N28[3]
2	IO	P25[3]
2	IO	U26[3]
2	IO	U30
2	IO	U32[3]
2	IO	U34
2	IO_D2	M30
2	IO_DOUT_BUSY_L86P_YY	D32
2	IO_DIN_D0_L86N_YY	J27
2	IO_L87P_Y	E31
2	IO_L87N_Y	F30
2	IO_L88P_Y	G29
2	IO_L88N_Y	F32
2	IO_VREF_L89P_Y	E32
2	IO_L89N_Y	G30
2	IO_L90P	M25
2	IO_L90N	G31
2	IO_L91P_Y	L26
2	IO_L91N_Y	D33
2	IO_VREF_L92P_Y	D34